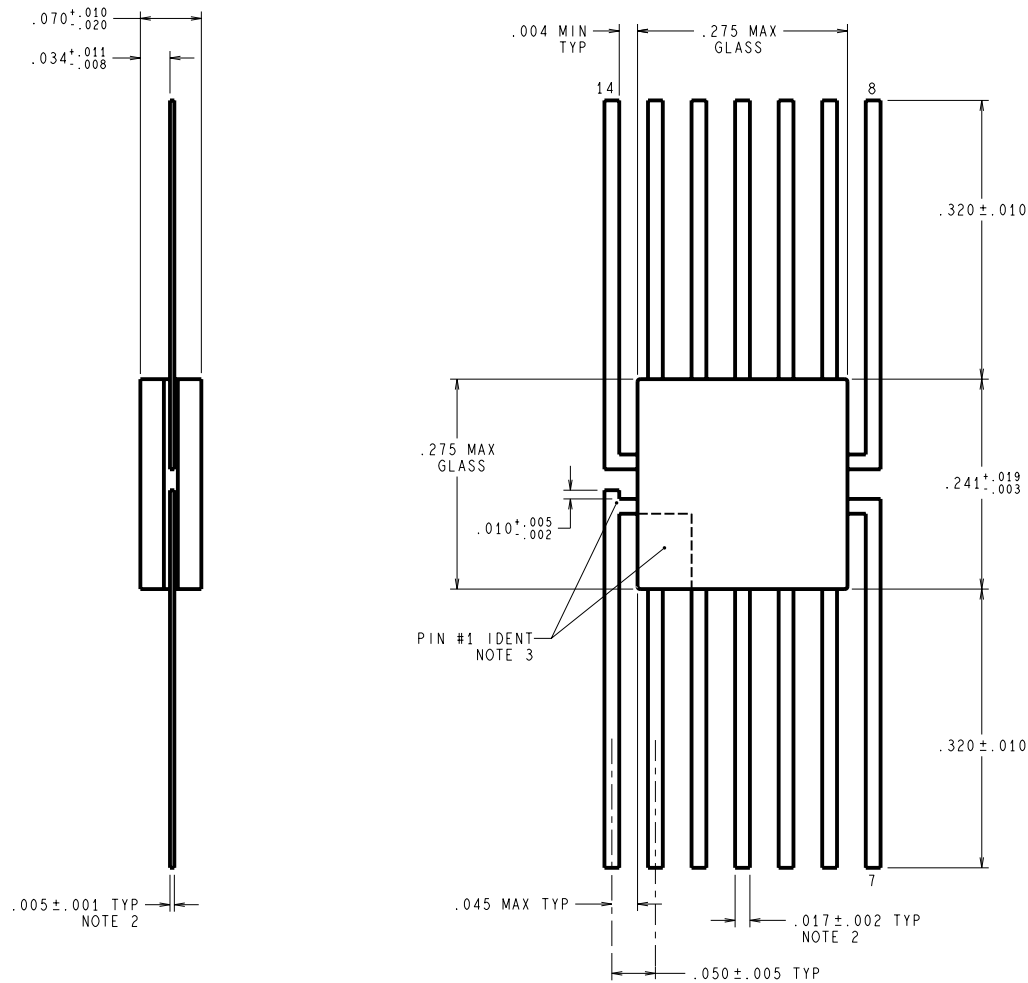


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
D	REVISE AND REDRAW PER NEW STANDARD.	10511	07/26/94	DEG/AP
E	LD WIDTH TOL $\pm .002$ WAS $\pm .020$; UPDATE MIL/AERO STAMP; ADD PIN #1 IDENT AREA; ADD TYP PER INPUT; ADD (SC) TO DWG #; ADD NOTE "DIMENSIONS ARE IN INCHES".	11559	08/27/1996	MS/



NOTES: UNLESS OTHERWISE SPECIFIED.

- LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-PRF-38535 TO A MINIMUM THICKNESS OF 200 MICROINCHES. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE.
- MAXIMUM LIMIT MAY BE INCREASED BY .003 INCHES AFTER LEAD FINISH APPLIED.
- LEAD 1 IDENTIFICATION SHALL BE:
 - A NOTCH OR OTHER MARK WITHIN THIS AREA
 - A TAB ON LEAD 1, EITHER SIDE
- NO JEDEC REGISTRATION AS OF 02/07/94.

DIMENSIONS ARE IN INCHES

MIL-PRF-38535
CONFIGURATION CONTROL

APPROVALS		DATE	National Semiconductor		
DRAWN	<i>D. E. Grady</i>	07/26/94	2900 Semiconductor dr., Santa Clara, CA 95052-8090		
DTG. CHK.			CERPACK, 14 LEAD		
ENGR. CHK.					
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-W14C	E
DO NOT SCALE DRAWING			SHEET 1 of 1		